

Amendments to the Claims

1. **(Currently Amended)** A method for polishing an object by using an abrading surface made of abrasive particles and a binder, said method comprising:

polishing the said object by the abrading surface while supplying a liquid not containing any abrasive particles for a determined time period; and

further polishing the said object by the abrading surface while supplying abrasive particles so as to perform additional removal of a surface material to uniformly remove a specific film thickness.

2. **(Currently Amended)** A method according to claim 1, wherein said further polishing to remove the additional removal of a surface material is performed with the said abrading surface by supplying a slurry containing abrasive particles to said the abrading surface to be polished.

3. **(Currently Amended)** A method according to claim 1, wherein said additional further polishing to remove the removal of a surface material comprises is performed by:

polishing while concurrently dressing the said abrading surface with a liquid not containing abrasive particles to thereby generate free abrasive particles therefrom.

Claim 4 (Canceled)

5. **(Currently Amended)** A polishing apparatus for polishing a surface of an object, said polishing apparatus comprising:

a holder for holding the said object;

an abrading surface comprising abrasive particles and a binder;

a mechanism for pressing the said surface of the said object to said abrading surface while producing a sliding motion over a polishing interface;

a device for supplying a liquid not containing abrasive particles to the said polishing interface; and

a surface material removal device for performing additional material removal by supplying abrasive particles on said abrading surface, said surface material removal device being integrally mounted in said polishing apparatus.

6. (Currently Amended) A polishing An apparatus according to claim 5, wherein said surface material removal device is a device for supplying a slurry containing abrasive particles to the said polishing interface.

7. (Currently Amended) A polishing An apparatus according to claim 5, wherein said surface material removal device is a device for dressing said abrading surface so as to release abrasive particles from said abrading surface.

8. (Currently Amended) A polishing An apparatus according to claim 5, further comprising: wherein said apparatus is provided with a

first polishing means for to perform polishing while supplying a liquid not containing abrasive particles to the said polishing interface; and

a second polishing means for to perform polishing while supplying a slurry containing abrasive particles to the said polishing interface.

Claims 9-53 (Canceled)

54. (Currently Amended) A method for polishing an object using an abrading surface made of abrasive particles and a binder binding the said abrasive particles, said method comprising:

dressing the said abrading surface to shape the said abrading surface by a dresser prior to a polishing process;

pressing the object against the said abrading surface; and

polishing the object by making a sliding motion between a surface of the object and the said abrading surface.

55. **(Currently Amended)** A method according to claim 54, wherein a surface roughness of the said abrading surface is less than $\pm 30\mu\text{m}$ after said dressing process.

56. **(Currently Amended)** A method according to claim 54, wherein the said abrading surface is a surface of an abrading plate, the abrading plate being which is shaped by pressing while in a container in during a manufacturing process of the abrading plate same.

57. **(Currently Amended)** A method according to claim 54, wherein a ratio of the said abrasive particles and a material of the binder material is 1:x, where x is not less than $0,5$ 0,5 by volume (the binder material per 1 unit of the abrasive particles is not less than $0,5$ 0,5 unit), and proportions of the said abrasive particles, the said binder, and porosity are, respectively, not less than 10%, not more than 60% and 10-40% by volume.

58. **(Original)** A method according to claim 54, wherein said dressing process is conducted under supplying water.

59. **(Currently Amended)** A method according to claim 54, wherein the said dresser comprises diamond particles.

60. **(Currently Amended)** A method according to claim 59, wherein the dresser comprises the said diamond particles are electro-deposited in a nickel base.

61. **(Original)** A method according to claim 54, wherein said dressing process further comprises removing residual particles from the dressed abrading surface.

62. **(Currently Amended)** A method according to claim 61, wherein said removing process comprises pressing and rotating a flat tool against the said abrading surface.

63. **(Currently Amended)** A method according to claim 61, wherein the said flat tool comprises a blanket wafer, a quartz glass substrate, or a ceramic substrate.

64. **(Currently Amended)** A method according to claim 61, wherein said removing process comprises washing the said abrading surface using a brush while flowing a liquid thereon.

65. **(Currently Amended)** A method according to claim 61, wherein said removing process comprises applying a pressured fluid on the said abrading surface.

66. **(Currently Amended)** A method according to claim 65, wherein a said pressure of the pressured fluid is less than 5 kgPa.

67. **(Currently Amended)** A method according to claim 61, wherein said removing process comprises applying an ultrasonic fluid on the said abrading surface.

68. **(Currently Amended)** A method for polishing an object using an abrading surface made of abrasive particles and a binder binding the said abrasive particles, said method comprising:

dressing the said abrading surface by a dresser prior to a polishing process until a surface roughness of the said abrading surface is less than $\pm 30\mu\text{m}$; and

pressing the object against the said abrading surface and polishing the object by making a sliding motion between a surface of the object and the said abrading surface.

69. **(Currently Amended)** A method according to claim 68, wherein the said dresser comprises a diamond dresser having which size of diamond particles of is #100 size.

70. **(Currently Amended)** A method according to claim 68, wherein said dressing process is conducted by pressing the said dresser with a pressure of less than 100g/cm^2 .

71. **(Currently Amended)** A method for polishing an object using an abrading surface made of abrasive particles and a binder binding the said abrasive particles, said method comprising:

dressing the said abrading surface by a diamond dresser for moderately roughening the abrading surface;

pressing the object against the said abrading surface and polishing the object by making a sliding motion between a surface of the object and the said abrading surface, wherein a pressure between the said abrading surface and the said dresser is less than 100g/cm².

72. **(Currently Amended)** A method according to claim 71, wherein the said pressure of said dressing process is less than 50g/cm².

73. **(Currently Amended)** A method according to claim 71, wherein the said dresser comprises a diamond dresser having which size of diamond particles of is #200 size.

74. **(Currently Amended)** A method for polishing an object using an abrading surface made of abrasive particles and a binder binding the said abrasive particles, said method comprising:

polishing a surface of the object by pressing the object against the said abrading surface and making a sliding motion between the a surface of the object and the said abrading surface; and

dressing the said abrading surface by a dresser for roughening the abrading surface during said polishing process to generate free abrasive particles from the said abrading surface.

75. **(Original)** A method according to claim 74, wherein said polishing process comprises a first stage polishing which is conducted without dressing, and a second stage polishing which is conducted with dressing.

76. **(Currently Amended)** A method according to claim 74, wherein said polishing process operation is conducted while supplying a liquid not containing abrasive particles.

Claim 77 (Canceled)

78. **(Currently Amended)** A method for polishing an object having a raised and depressed pattern thereon, said method comprising:

pressing the object against an abrading surface comprising abrasive particles and a binder binding the said abrasive particles;

polishing a the surface of the object by making a sliding motion between the a surface of the object and the said abrading surface; and

supplying a liquid including a surface activator during the said sliding motion.

Claims 79-81 (Canceled)

82. **(Currently Amended)** An apparatus for polishing an object using an abrading surface made of abrasive particles and a binder binding the said abrasive particles, said apparatus comprising:

a holder for holding the object;

a mechanism for pressing the object against the said abrading surface and making a sliding motion between a surface of the object and the said abrading surface; and

a dresser for dressing the said abrading surface prior to a polishing process to shape the said abrading surface.

83. **(Currently Amended)** An apparatus according to claim 82, wherein a surface roughness of the said abrading surface is less than $\pm 30\mu\text{m}$ after the said dressing process.

84. **(Currently Amended)** An apparatus according to claim 82, wherein the said abrading surface is a surface of an abrading plate, the abrading plate being which is shaped by pressing while in a container in during a manufacturing process of the abrading plate same.

85. **(Currently Amended)** An apparatus according to claim 84, wherein a ratio of the said abrasive particles and the binder material is $1:x$, where x is not less than 0.5 0.5 by volume (the binder material per 1 unit of the abrasive particles is not less than 0.5 0.5 unit), and proportions of the said

abrasive particles, the said binder, and porosity are, respectively, not less than 10%, not more than 60% and 10-40% by volume.

86. **(Currently Amended)** An apparatus according to claim 82, further comprising a device for supplying water during the said dressing process.

87. **(Original)** An apparatus according to claim 82, wherein said dresser comprises diamond particles.

88. **(Currently Amended)** An apparatus according to claim 87, wherein said dresser comprises said diamond particles are electro-deposited in a nickel base.

89. **(Original)** An apparatus according to claim 82, further comprising a residual particles removing device for removing residual particles from the dressed abrading surface.

90. **(Currently Amended)** An apparatus according to claim 89, wherein said residual particles removing device comprises a flat tool for pressing and rotating against the said abrading surface.

91. **(Original)** An apparatus according to claim 90, wherein said flat tool comprises a blanket wafer, a quartz glass substrate, or a ceramic substrate.

92. **(Currently Amended)** An apparatus according to claim 89, wherein said residual particles removing device comprises a brush for washing the said abrading surface while flowing a liquid thereon.

93. **(Currently Amended)** An apparatus according to claim 89, wherein said residual particles removing device comprises a pressured fluid ejector for applying a pressured fluid on the said abrading surface.

94. **(Currently Amended)** An apparatus according to claim 93, wherein a said pressure of the pressurized fluid is less than 5 kgPa.

95. **(Currently Amended)** An apparatus according to claim 89, wherein said residual particle removing device comprises an ultrasonic source for applying an ultrasonic energy to a fluid on the said abrading surface.

96. **(Currently Amended)** An apparatus for polishing an object using an abrading surface made of abrasive particles and a binder binding the said abrasive particles, said apparatus comprising:
a holder for holding the object;
a mechanism for pressing the object against the said abrading surface and making a sliding motion between a surface of the object and the said abrading surface; and
a diamond dresser for dressing and roughening the said abrading surface,
wherein a pressure applied by said dresser against the said abrading surface is less than 100g/cm².

97. **(Currently Amended)** An apparatus according to claim 96, wherein the said pressure of said dresser is less than 50g/cm².

98. **(Currently Amended)** An apparatus according to claim 97, wherein said dresser comprises a diamond dresser having which size of diamond particles of particle is #200 size.

99. **(Currently Amended)** An apparatus for polishing an object using an abrading surface made of abrasive particles and a binder binding the said abrasive particles, said apparatus comprising:
a holder for holding the object;
a mechanism for polishing a the surface of the object by pressing the object against the said abrading surface and making a sliding motion between a surface of the object and the said abrading surface;

a dresser for dressing the said abrading surface for roughening the abrading surface by a dresser during the said polishing process to generate free abrasive particles from the said abrading surface.

100. **(Currently Amended)** An apparatus according to claim 99, further comprising a controller for sending a signal for switching between a first stage polishing which is conducted without dressing, and a second stage polishing which is conducted with dressing.

101. **(Currently Amended)** An apparatus according to claim 99, wherein the said polishing operation process is conducted while supplying a liquid not containing abrasive particles.

102. **(Currently Amended)** A method according to claim 1, wherein the said object is a semiconductor wafer having a raised and depressed pattern thereon.

103. **(Currently Amended)** A method according to claim 1, wherein the said object is held by a same holder during said polishing and said further polishing.

104. **(Original)** An apparatus according to claim 5, wherein said abrading surface comprises a surface of an abrading plate.

105. **(New)** A method according to claim 74, wherein the dresser comprises a diamond dresser.

106. **(New)** An apparatus according to claim 99, wherein the dresser comprises a diamond dresser.